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(54) Title: THERMOPLASTIC MOLDING COMPOSITIONS

(57) Abstract: Thermoplastic molding compositions, comprising: A) at least one rubber-free copolymer in which no hydroxyl group, acid group, amino group, or anhydride group is present, based on at least one vinylaromatic monomer (a1) and at least one comonomer (a2), B) at least one rubber-free polymer in which at least one hydroxyl group, acid group, or amino group is present, C) from 3 to 50% by weight, based on the total weight of the molding composition, of at least one rubber, D) at least one terpolymer, obtainable from d1) at least one vinylaromatic monomer, d2) at least one C₁-C₄-alkyl (meth)acrylate or (meth)acrylonitrile, and d3) from 0.4 to 4% by weight, based on the total weight of the terpolymer, of at least one monomer in which an α,β-unsaturated anhydride is present, and E) at least one compound having at least two isocyanate groups.